Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1-67. (Canceled)

68. (Currently Amended) An IC module, comprising:

an antenna coil having antenna terminals;

a substrate for an IC module;

an IC chip mounted on the substrate for the IC module and having antenna terminals; and

a contact-terminal plate mounted on the substrate for the IC module and having a plurality of contact terminals;

wherein the plurality of contact terminals includes terminals C1-C8 conforming to ISO 7816 standard; and

said IC module includes a contact terminal CE1 and a contact terminal CE2 connected to the antenna terminals of the IC chip, wherein said terminals CE1 and CE2 of the contact terminal plate are adapted to be connected to the antenna terminals of the antenna coil, and

a pair of U-shaped circuits are formed so as to surround the IC chip on a surface of the substrate for the IC module opposite a surface of the substrate for the IC module on which the contact terminal plate is mounted in a manner where the IC chip is placed at a center portion of an area surrounded by the pair of U-shaped circuits, the contact terminals CE1 and CE2 being connected to the U-shaped circuits, respectively, and the U-shaped circuits being connected to the antenna terminals of the IC chip, respectively.

69. (Previously Presented) The IC module according to claim 68, wherein said contact terminal CE1 is disposed between said terminal C1 and said terminal C5 among said

eight contact terminals C1-C8, and said contact terminal CE2 is disposed between said terminals C4 and C8 among said eight contact terminals C1-C8.

70. (Previously Presented) The IC module according to claim 68, wherein the contact terminals CE1 and CE2 are those to be connected to an antenna coil formed in a SIM holder or in an IC card holder.

71. (Previously Presented) The IC module according to claim 68, wherein the antenna terminals of the IC chip are connected to the contact terminals CE1 and CE2 by wire bonding.

72. (Previously Presented) The IC module according to claim 68, wherein the antenna terminals of the IC chip are connected to the contact terminals CE1 and CE2 via through holes.

73. (Previously Presented) The IC module according to claim 68, wherein the IC chip has a contact interface conforming to ISO 7816-2 and ISO 7816-3, a noncontact interface conforming to ISO 14443, and a USB contact interface.

74. (Previously Presented) The IC module according to claim 68, wherein antenna-terminal plates are connected to said antenna-terminal plates of the IC chip, and said antenna-terminal plates are adapted to be connected to antenna-terminals of the antenna coil.

75. (Previously Presented) An IC card comprising an IC module according to claim 68, and a card holding the IC module.

76. (Previously Presented) A SIM comprising an IC card according to claim 75.

77. (Previously Presented) The SIM according to claim 76, wherein the contact terminals CE1 and CE2 are those to be connected to an antenna coil formed in a SIM holder.

78. (Previously Presented) The SIM according to claim 76, wherein one or some of a half-length photograph, a name and a number are printed on a surface of the SIM base opposite a surface of the SIM base on which the contact terminal plate is mounted.

79. (Currently Amended) An IC module comprising:

a substrate for an IC module;

an IC chip mounted on the substrate for the IC module; and

a contact-terminal plate provided with a plurality of contact terminals and mounted on the substrate for the IC module;

wherein a pair of U-shaped circuits are formed so as to surround the IC chip on a surface of the substrate for the IC module opposite a surface of the substrate for the IC module on which the contact-terminal plate is mounted in a manner where the IC chip is placed at a center portion of an area surrounded by the pair of U-shaped circuits, and the U-shaped circuits are connected to antenna terminals of the IC chip, respectively and connected to the contact terminals of the contact-terminal plate via through holes, and the terminals of the IC chip other than the antenna terminals which are connected to the U-shaped circuits are connected to the connecting pads placed on the surface of the substrate for the IC module on which the U-shaped circuits are formed through bonding wires.

80. (Previously Presented) The IC module according to claim 79, wherein the U-shaped circuits are connected to an antenna coil formed in a card.

81. (Previously Presented) The IC module according to claim 79, wherein the U-shaped circuits are connected to the contact terminals, not used for contact communication, among the plurality of contact terminals.

82. (Previously Presented) The IC module according to claim 81, wherein the U-shaped circuits are connected to terminals C4 and C8 among eight contact terminals C1 to C8.

83. (Previously Presented) The IC module according to claim 82, wherein the U-shaped circuits are connected to the terminals C4 and C8 via through holes.

84. (Previously Presented) The IC module according to claim 79, wherein the U-shaped circuits are connected to antenna terminals of the IC chip by wire bonding.

85. (Previously Presented) The IC module according to claim 79, wherein the U-shaped circuits are connected to contact terminals CE1 and CE2, the contact terminals CE1 and CE2 being connected to antenna terminals of the IC chip.

86. (Previously Presented) The IC module according to claim 85, wherein the U-shaped circuits are connected to contact terminals CE1 and CE2 via through holes, respectively.

87. (Previously Presented) The IC module according to claim 85, wherein the U-shaped circuits are connected to the antenna terminals of the IC chip by wire bonding.

88. (Previously Presented) The IC module according to claim 85, wherein the contact terminals CE1 and CE2 are connected to an antenna coil formed on a SIM holder or an IC card holder.

89. (Previously Presented) A SIM comprising an IC module according to claim 79.

90. (Previously Presented) An IC card comprising an IC module according to claim 79.